

#4/Pre-Amendment  
4-18-02  
JH

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

**WATANABE, KENICHI**

Serial No.: 09/987,012

Filed: November 13, 2001

P.T.O. Confirmation No.: 6363

**ATTN: BOX MISSING PARTS**

Group Art Unit: 2811

**FOR. SEMICONDUCTOR WAFER DEVICE HAVING SEPARATED  
CONDUCTIVE PATTERNS IN PERIPHERAL AREA AND ITS  
MANUFACTURING METHOD**

**PRELIMINARY AMENDMENT**

**Commissioner for Patents  
Washington, D.C. 20231**

February 20, 2002

Sir:

Prior to examination on the merits, please amend the above-identified application as follows:

**IN THE SPECIFICATION:**

Amend the specification as follows:

**Please replace the paragraph beginning at page 5, line 22, with the following  
rewritten paragraph:**

**Figs. 8A to 8C are cross sectional views showing a modification of the embodiment  
shown in Figs. 6A to 6D.**

A1